NOTE1:100μs pulse, 100Hz frequency
NOTE2:AC for 1minute, R.H=40~60%

ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F				

Characteristics Curves

FIG.1: Forward Current vs. Ambient Temperature

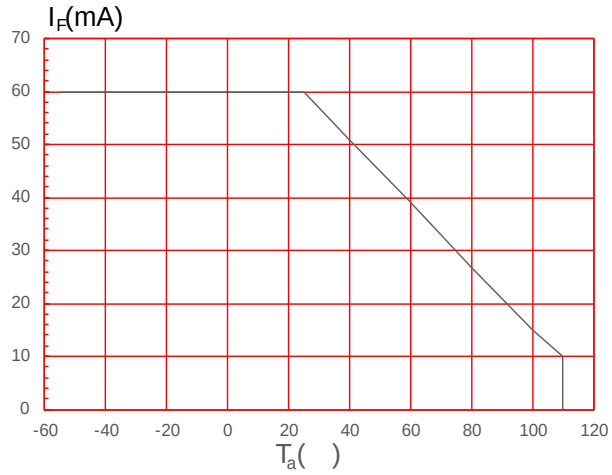
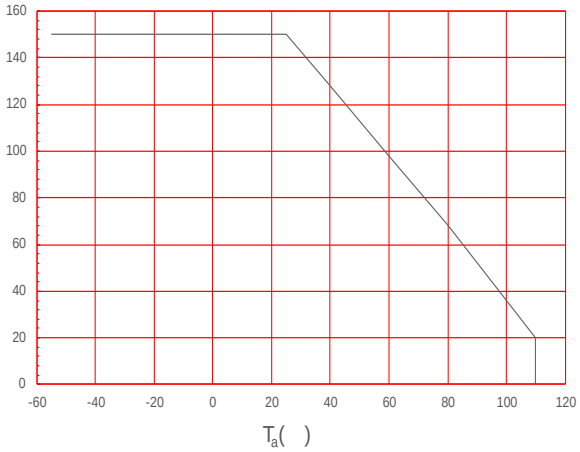


FIG.2: Collector Power Dissiption vs. Ambient Temperature



TestCircuits

FIG.11: Test Circuits of Response Time

FIG.12: Curves of Response Time

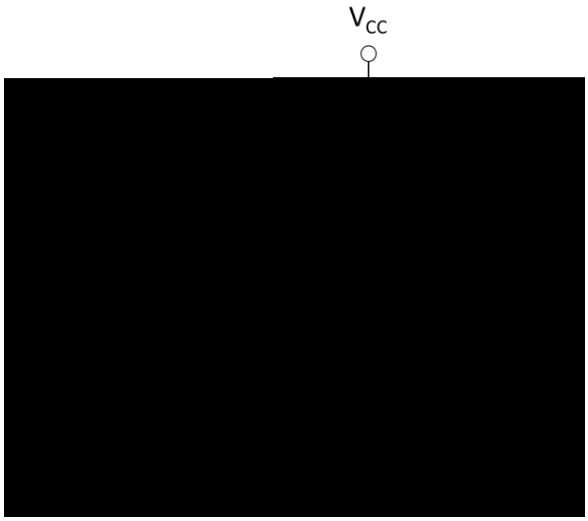
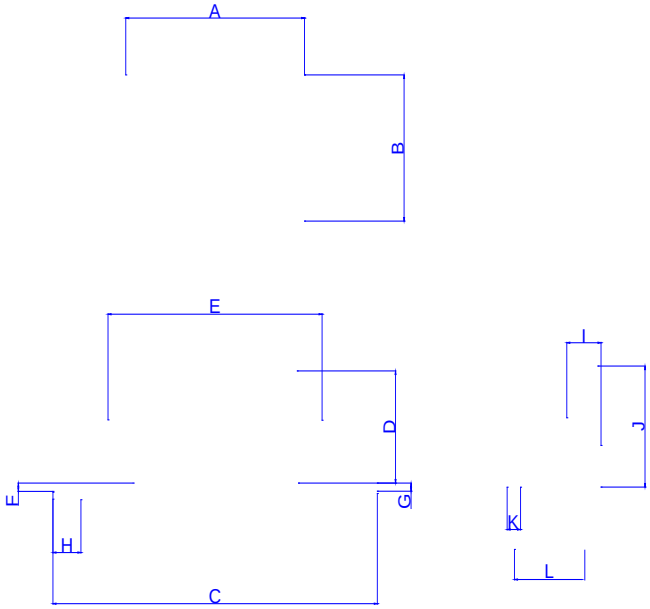


FIG.13: Test Circuits of Frequency Response

Package Dimension (Unit: mm)

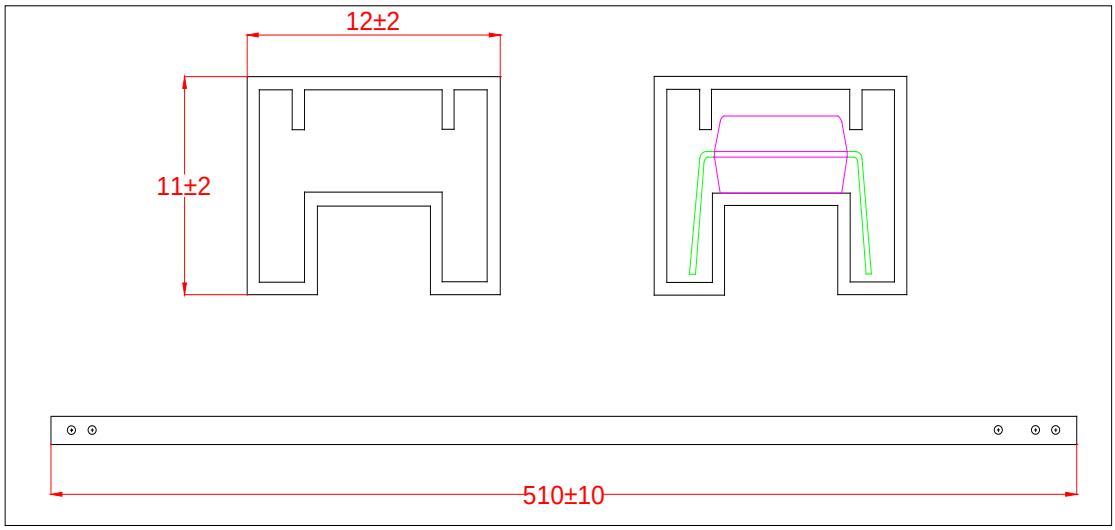
Option SLM Type: DimensionsMillimetersInches



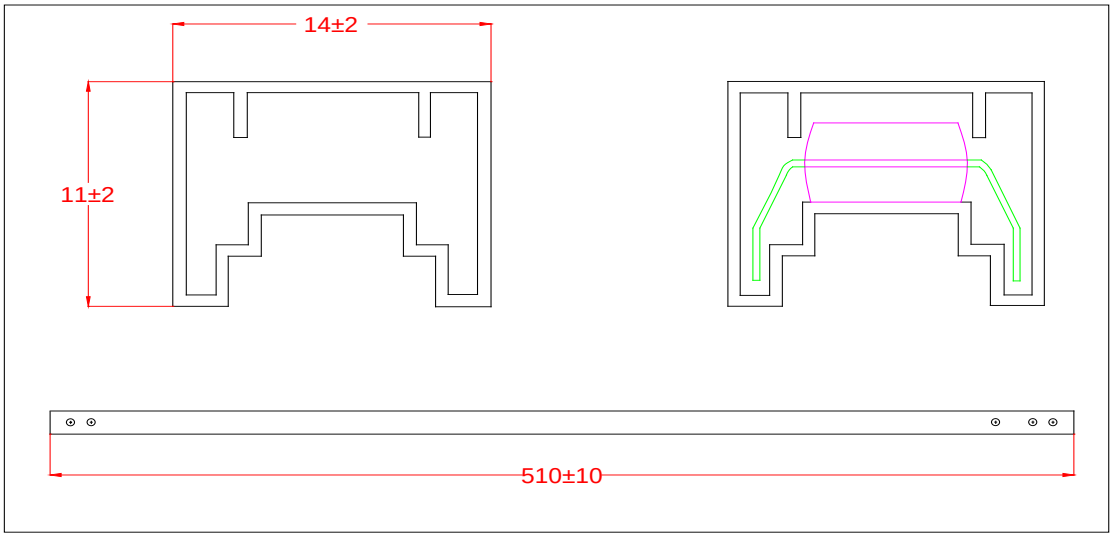
Optio Co

TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Standard DIP

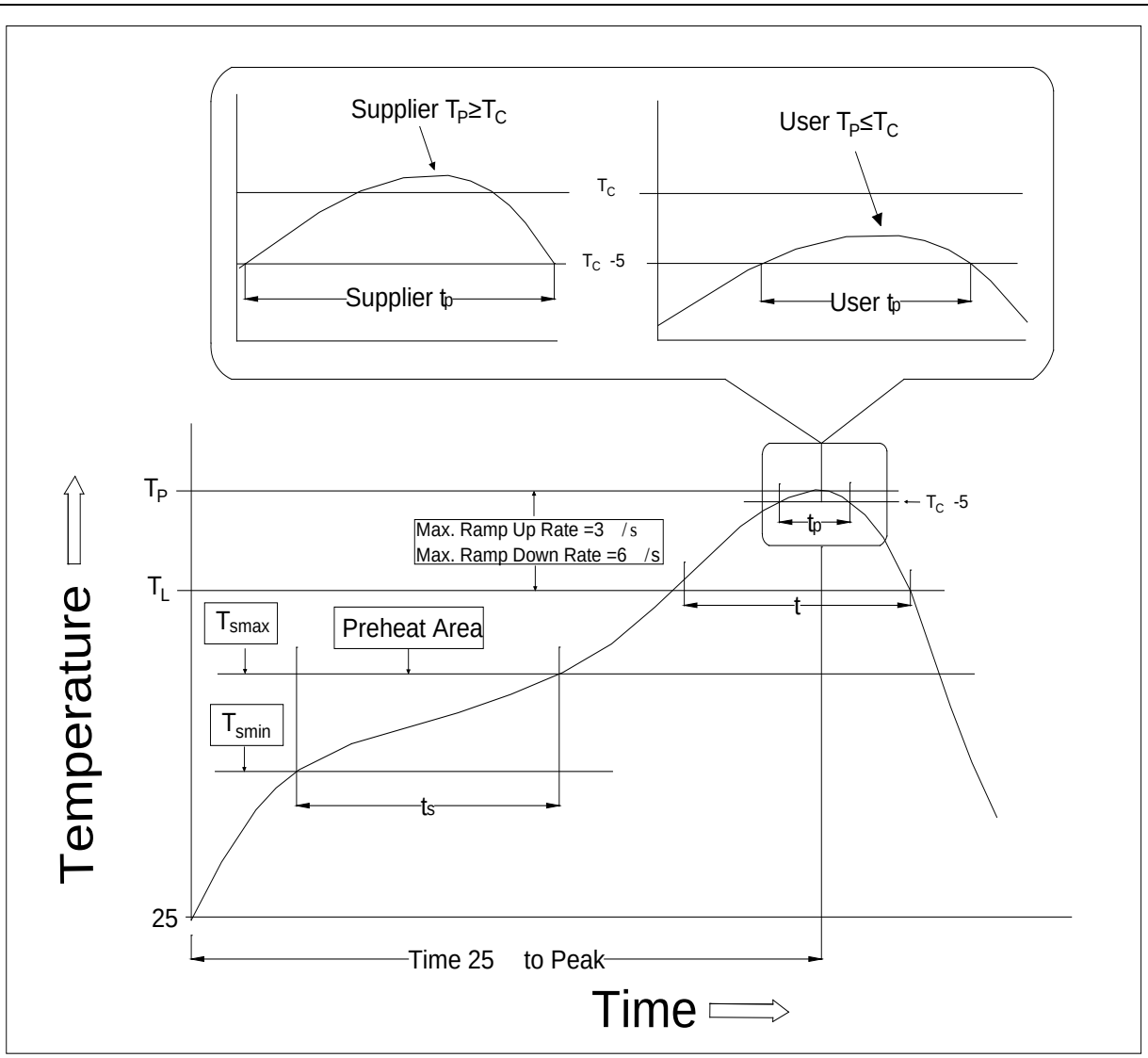


Option M



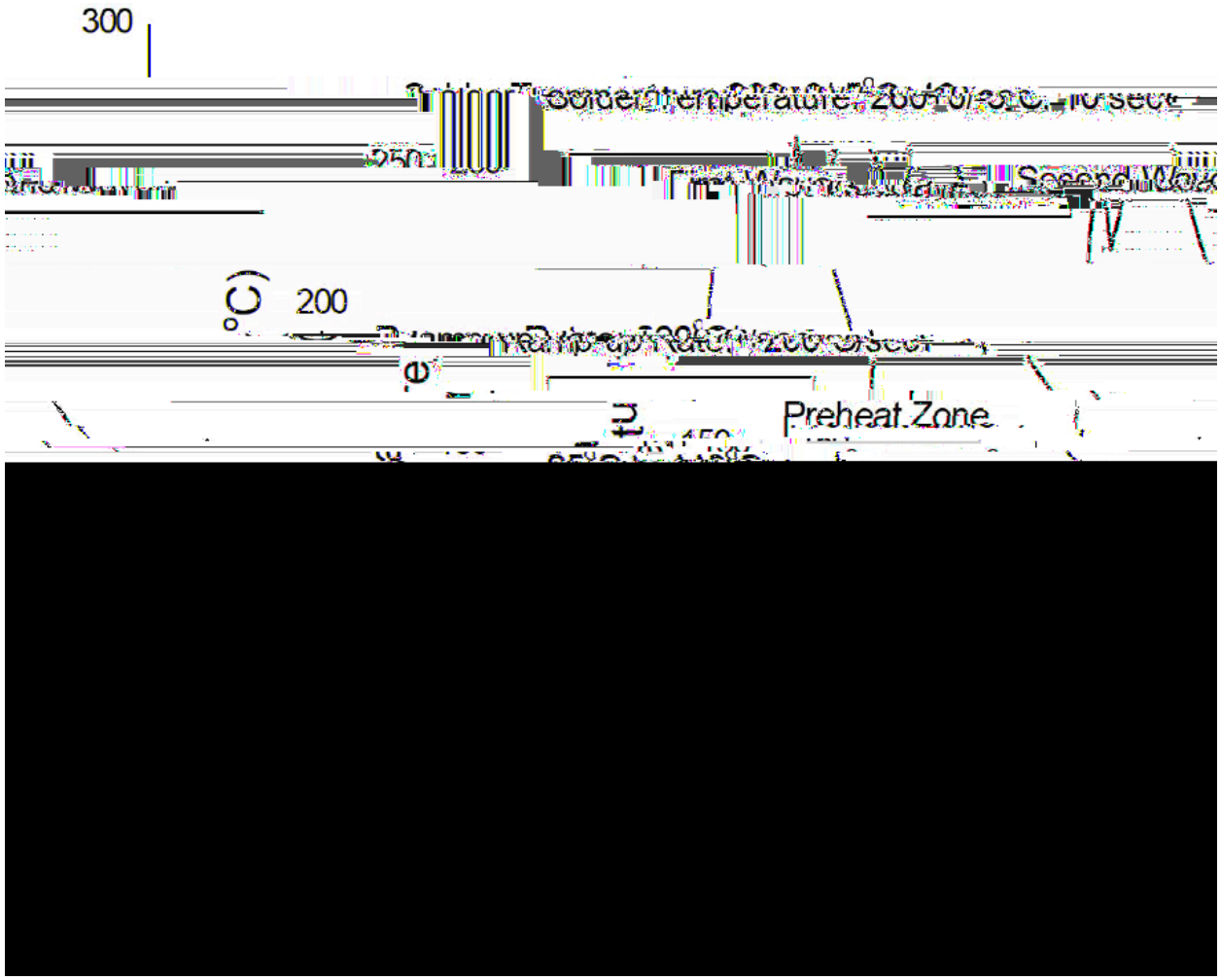
JOC814X1

REFLOW INFORMATION



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100	150
Temperature Max. (Tsmax)	150	200
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3 /second max.	3 /second max.
Liquidus Temperature (TL)	183	217
Time (tL) Maintained Above (TL)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (tP) within 5 of 260	10 seconds	10 seconds
Ramp-down Rate (TP to TL)	3-6 /second	3-6 /second
Time 25 to Peak Temperature	6 minutes max.	8 minutes max.

WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON	
Soldering Temperature	360–5
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent